Please amend the specification as follows.

Please substitute the following paragraph for paragraph **[0023]** on page 7 of the substitute specification.

-- **[0023]**   Figure 7, including Figures 7A and 7B, is a flow chart for explaining an example of offset measurement with the surface position detecting method of the present invention, as well as a sequence for surface position corrective drive during exposure of the shots. --

Please substitute the following paragraph for paragraph **[0024]** on page 7 of the substitute specification.

-- **[0024]**   Figure 8, including Figures 8A and 8B, is a flow chart for explaining an example of a sequence for surface position correcting drive during exposure, when there is a fault in the wafer flatness in the alternate scan.

Please substitute the following paragraph for paragraph **[0041]** on page 13 of the substitute specification.

-- **[0041]**   Figure 7, including Figures 7A and 7B, shows an example of a correction sequence according to the present invention. At step 101, a start command is received. At step

102, a wafer is loaded on a wafer stage, and it is attracted to and held by a chuck. Subsequently, for measurement of the surface shape (plural surface positions) inside a process region (shot region) of the wafer to be exposed, with regard to six sample shot regions, such as depicted by hatching in Figure 3, for example, pre-scan measurement is carried out with respect to each shot region, and the results are stored into a memory. Namely, at step 103, pre-scan measurement in the up direction is carried out and, at step 104, pre-scan measurement in the down direction is carried out in the same region as in the up-direction scan at step 103. The operation at step 103 and step 104 is carried out repeatedly to all the sample shot regions (six sample shot regions in this example) through step 105. In each sample shot region, the pre-scan measurement may be made plural times with respect to each direction. --

Please substitute the following paragraph for paragraph **[0051]** on page 16 of the substitute specification.

-- **[0051]**   Such an embodiment will be described with reference to the flow chart of Figure 8, which includes Figures 8A and 8B. In Figure 8, a start command is received at step 201. At step 202, a wafer is loaded on a wafer stage, and it is attracted to and held by a chuck. Subsequently, for measurement of the surface shape (plural surface positions) inside a chip region or process region (shot region) of the wafer to be exposed, with regard to plural sample shot regions, such as depicted by hatching in Figure 3, for example, pre-scan measurement is carried out with respect to each shot region, and the results are stored into a memory. Namely, at step 203, pre-scan measurement in the up direction is carried out and, at step 204, pre-scan measurement in the down direction is carried out in the same region as in the up-direction scan at

step 203. The operation at step 203 and step 204 is carried out repeatedly to all the sample shot regions (six sample shot regions, in this example). --

Please substitute the following paragraph for paragraph **[0054]** on page 17 of the substitute specification.

-- **[0054]** If, at step 207, any of the up/down direction differences is larger than the predetermined amount (YES), it is concluded that this is because of a defect, or the like, of the wafer flatness due to process factor or chuck factor, and the sequence goes to step 211. At step 211, offset correction values toward the optimum image plane position are calculated in accordance with the calculation method of the first embodiment, and on the basis of the up/down scan measurement data with the data concerning the error point in question being excluded. When the correction value calculation is completed at step 208 or step 211, exposure is carried out at step 209, while at step 209, during the scan exposure, the surface position detected values at the detection points for the surface position detection are corrected by the correction values corresponding to the pattern structure, for example, at the detection point, and additionally, the process region to be exposed is registered with the exposure image plane on the basis of the thus corrected surface position detected values. After this, at step ~~212~~ 216, the chuck attraction is released, and the wafer is unloaded. Following that, ~~and~~ the procedure is finished in step 212.